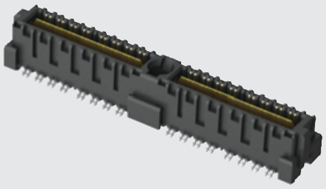
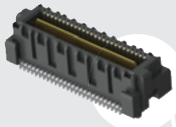
QMS–032–06.75–L–D–DP–A





QMS–026–06.75–L–D–A

(0,635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:
Liquid Crystal Polymer
Terminal & Ground Plane Material:
Phosphor Bronze
Plating:
Au over 50µ" (1,27 µm) Ni
(Tin on Ground Plane Tail)
Current Rating:
Contact:
2.6 A per pin
(1 pin powered per row)
Ground Plane:
15.7 A per ground plane
(1 ground plane powered)
Voltage Rating:
300 VAC mated with QFS
Operating Temp:
-55°C to +125°C
RoHS Compliant: Yes

Processing:

Lead–Free Solderable: Yes
SMT Lead Coplanarity:
(0,10 mm) .004" max (026-052)
(0,15 mm) .006" max (078)
Board Stacking:
For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

Industry Standards

SUMIT™
PCI/104-Express™

Protocols Supported

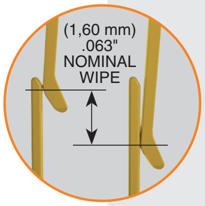
100 GbE
Fibre Channel
XAUI
PCI Express®
SATA

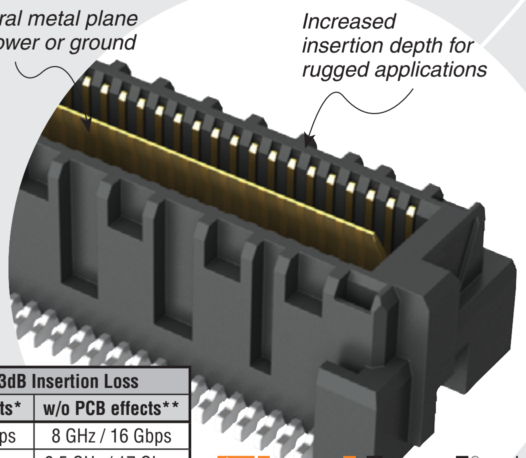
Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QFS

Cable Mates:
6QCD





Integral metal plane for power or ground

Increased insertion depth for rugged applications

ALSO AVAILABLE (MOQ Required)

- Other platings
- Guide Posts
- Without PCB Alignment Pins (05.75 and 06.75 only)
- Hot Pluggable
- 64 (-DP) and 104 positions per row

Contact Samtec.

QMS/QFS 10 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	–D	9 GHz / 18 Gbps	8 GHz / 16 Gbps
Differential Pair Signaling	–D	8 GHz / 16 Gbps	8.5 GHz / 17 Gbps
Differential Pair Signaling	–DP	7.5 GHz / 15 Gbps	9 GHz / 18 Gbps

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QMS or contact sig@samtec.com

Final Inch® CERTIFIED 28+ Gbps

QMS – PINS PER ROW NO. OF PAIRS – LEAD STYLE – PLATING OPTION – TYPE – A – OTHER OPTION

PINS PER ROW / NO. OF PAIRS

–026, –052, –078
(52 total pins per bank = –D)

–016, –032, –048
(16 pairs per bank = –D–DP)

(–078 & –048 Not available with –09.75 lead style)

LEAD STYLE

Specify LEAD STYLE from chart

PLATING OPTION

–L
(–05.75 and –06.75 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane
(Tin on Signal Pin tails, and Ground Plane tails)

–SL
(–09.75 lead style only)
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane
(Tin on Signal Pin tails, and Ground Plane tails)

TYPE

–D
= Single-Ended

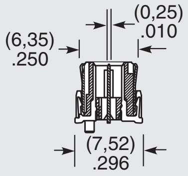
–D–DP
= Differential Pair

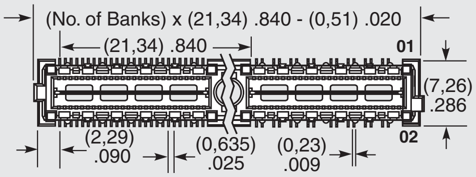
OTHER OPTION

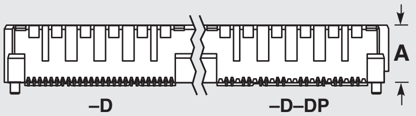
–K
= (5,50 mm) .217" DIA Polyimide film Pick & Place Pad

MATED HEIGHT*			
LEAD STYLE	A	QFS LEAD STYLE	
		–04.25	–06.25
–05.75	(5,38) .212	10 mm	12 mm
–06.75	(6,35) .250	11 mm	13 mm
–09.75	(9,35) .368	14 mm	16 mm

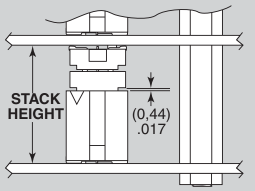
*Processing conditions will affect mated height.







APPLICATION



Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm